

SOT259-2

ceramic pin grid array package; 120 pins; body 33.5 x 33.5 x 2.6 mm

8 February 2016

Package information

1. Package summary

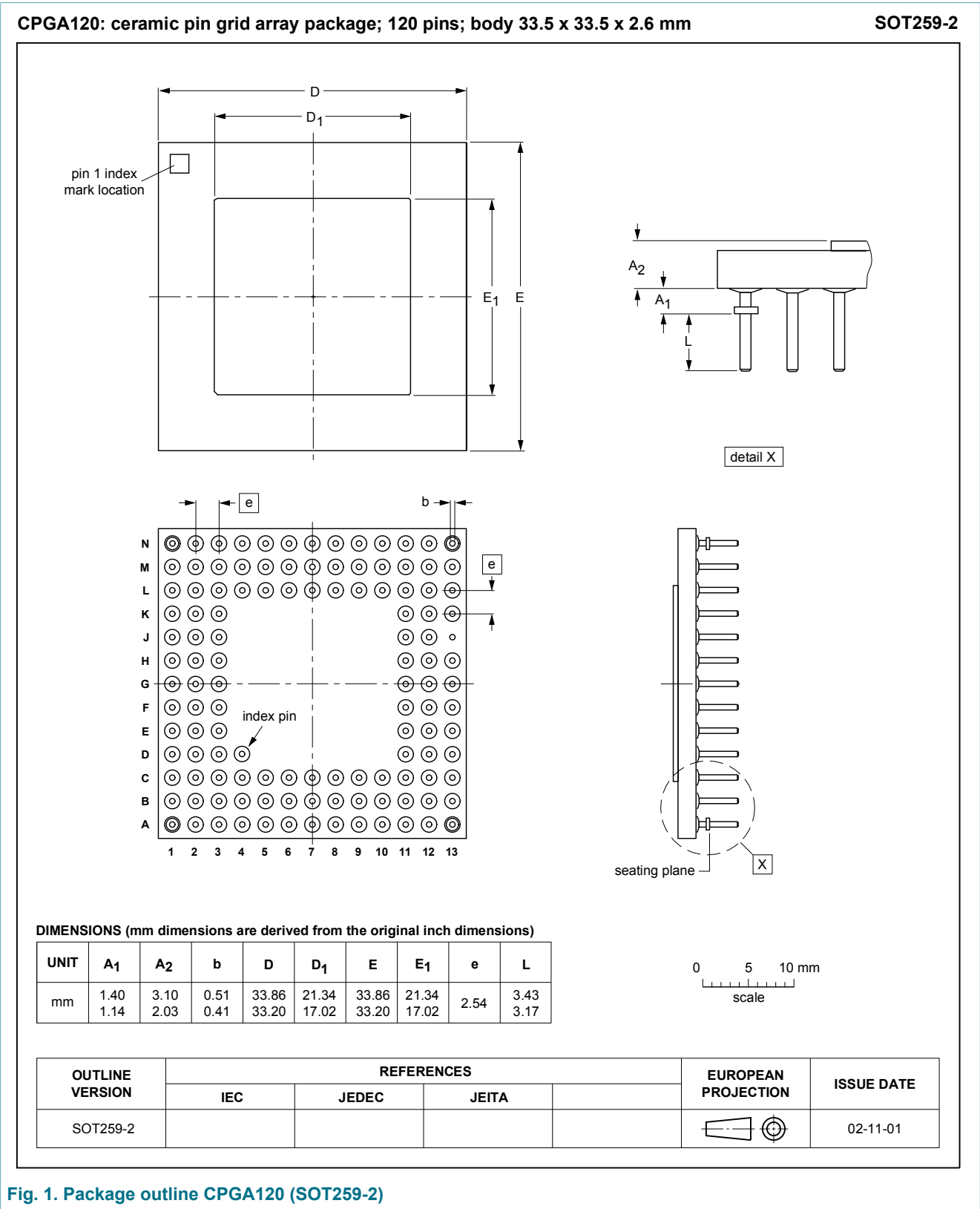
Terminal position code	B (bottom)
Package type descriptive code	CPGA120
Package type industry code	CPGA120
Package style descriptive code	CPGA (ceramic pin grid array)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	T (through-hole mount)
Issue date	1-11-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		33.2	-	33.5	33.86	mm
E	package width		33.2	-	33.5	33.86	mm
A ₂	package height		2.03	-	2.6	3.1	mm
n ₂	actual quantity of termination		-	-	120	-	



2. Package outline



3. Legal information

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